



National Standards Authority of Ireland

IRISH STANDARD

I.S. EN 62137:2005

ICS 31.190

**ENVIRONMENTAL AND ENDURANCE
TESTING - TEST METHODS FOR
SURFACE-MOUNT BOARDS OF AREA ARRAY
TYPE PACKAGES FBGA, BGA, FLGA, LGA,
SON AND QFN (IEC 62137:2004)**

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EUROPEAN STANDARD

EN 62137

NORME EUROPÉENNE

EUROPÄISCHE NORM

August 2004

ICS 31.190

Incorporates Corrigendum February 2005

English version

**Environmental and endurance testing -
Test methods for surface-mount boards of area array type packages
FBGA, BGA, FLGA, LGA, SON and QFN
(IEC 62137:2004)**

Essais d'environnement et d'endurance –
Méthodes d'essai pour les cartes
à montage en surface de boîtiers
de type matriciel FBGA, BGA, FLGA,
LGA, SON et QFN
(CEI 62137:2004)

Umwelt- und Dauerprüfung -
Prüfverfahren für in
Oberflächenmontagetechnik bestückte
Leiterplatten mit Area-Array-
Bauelementen der Bauformen
FBGA, BGA, FLGA, LGA, SON und QFN
(IEC 62137:2004)

This European Standard was approved by CENELEC on 2004-07-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Cyprus, Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Slovakia, Slovenia, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 91/444/FDIS, future edition 1 of IEC 62137, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62137 on 2004-07-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2005-04-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2007-07-01

Annex ZA has been added by CENELEC.

The contents of the corrigendum of February 2005 have been included in this copy.

Endorsement notice

The text of the International Standard IEC 62137:2004 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-44	NOTE	Harmonized as EN 60068-2-44:1995 (not modified).
IEC 60749-1	NOTE	Harmonized as EN 60749-1:2003 (not modified).
IEC 60749-20	NOTE	Harmonized as EN 60749-20:2003 (not modified).
IEC 61189-3	NOTE	Harmonized as EN 61189-3:1997 (not modified).
IEC 61760-1	NOTE	Harmonized as EN 61760-1:1998 (not modified).
IEC 61190-1-1	NOTE	Harmonized as EN 61190-1-1:2002 (not modified).
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2:2002 (not modified).
IEC 61190-1-3	NOTE	Harmonized as EN 61190-1-3:2002 (not modified).

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE Where an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	1988	Environmental testing Part 1: General and guidance	EN 60068-1	1994 ¹⁾
IEC 60191-6-2	2001	Mechanical standardization of semiconductor devices Part 6-2: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for 1,50 mm, 1,27 mm and 1,00 mm pitch ball and column terminal packages	EN 60191-6-2	2002
IEC 60191-6-5	2001	Part 6-5: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine-pitch ball grid array (FBGA)	EN 60191-6-5	2001
JEITA ETR-7001	1998	Terms and definitions for surface mount device	-	-

¹⁾ EN 60068-1 includes corrigendum October 1988 + A1:1992 to IEC 60068-1.

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